L Number	Hits	S arch Text	DB	Time stamp
	0	(surface near (m unt rm uting r m unted) n ar (package or packaging)).ti,ab,clm. and (l d or (light near miting n ar (diod or d vi))).ti,ab, lm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:27
	0	substrate.ti,ab,clm. (surface near (mount or mouting or mounted) near (package or packaging)).ti,ab,clm. and (led or (light near emitting near (diode or device))).ti,ab,clm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:28
	74	(surface near (mount or mouting or mounted) near (package or packaging)) and (led or (light near emitting near (diode or device))) and (seal or sealing or adhesive) and (solder or soldering) and (metal or gold or silver or conductive or conducting) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:28
	9	(surface near (mount or mounting or mounted)).ti,ab,clm. and (led or (light near emitting near (diode or device))).ti,ab,clm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:30
•	613	(surface near (mount or mounting or mounted)).clm. and (led or (light near emitting near (diode or device))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:30
	6	(surface near (mount or mounting or mounted)).clm. and (led or (light near emitting near (diode or device))).clm. and ((first or upper or lower or top or bottom or two) near (gold or silver or metal or conductive or conducting) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:34
•	3	(surface near (mount or mounting or m unt d)) near5 (I d or (light n ar emitting near (di de or devic))). Im. and ((first or upp r r I wer or t p or b ttom r tw) n ar (g ld r silver or metal or conducting) n ar layer).clm.	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2004/06/22 15:34

•	3	((surface n ar (mount or m unting or	USPAT;	2004/06/22
		m unted)) near5 (led or (light n ar mitting	US-PGPUB;	15:35
		n ar (diod r device)))).clm. and ((first r	EPO; JPO;	
		upper or I wer or top r bott m or two)	DERWENT;	
		near (gold or silver or m tal r onductive	IBM_TDB	
		or c nducting) near layer).clm.		
_	3	((surface near (mount or mounting or	USPAT;	2004/06/22
_		mounted)) near5 (led or (light near emitting	US-PGPUB;	15:35
		near (diode or device)))).clm. and ((first or	EPO; JPO;	10.00
		upper or lower or top or bottom or two)	DERWENT;	
	1	near2 (gold or silver or metal or conductive		
			IBM_TDB	
	9	or conducting) near layer).clm.	HODAT	2004/06/22
-	3	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near5 (led or (light near emitting	US-PGPUB;	15:36
		near (diode or device)))).clm. and ((first or	EPO; JPO;	
		upper or lower or top or bottom or two)	DERWENT;	
		near2 (gold or silver or metal or conductive	IBM_TDB	
	_	or conducting) near2 layer).clm.		
-	3	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:36
		emitting near (diode or device)))).clm. and	EPO; JPO;	
		((first or upper or lower or top or bottom or	DERWENT;	
		two) near2 (gold or silver or metal or	IBM_TDB	
		conductive or conducting) near2 layer).clm.		
-	4	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:36
		emitting near (diode or device)))).ti,ab,clm.	EPO; JPO;	
		and ((first or upper or lower or top or	DERWENT;	
		bottom or two) near2 (gold or silver or	IBM_TDB	
		metal or conductive or conducting) near2		
		layer).clm.		
-	6	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:38
		emitting near (diode or device)))).ti,ab,clm.	EPO; JPO;	
		and ((first or upper or lower or top or	DERWENT;	
		bottom or two) near2 (gold or silver or	IBM_TDB	
		metal or conductive or conducting) near2		
		layer).ti,ab,clm.		
-	6	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:38
		emitting near (diode or device)))).ti,ab,clm.	EPO; JPO;	
		and ((first or second or upper or lower or	DERWENT;	
		top or bottom or two) near2 (gold or silver	IBM_TDB	
		or metal or conductive or conducting) near2	_	
		layer).ti,ab,clm.		
	952	((surface near (mount or mounting or	USPAT;	2004/06/22
-		•	,	
-		mounted)) near10 (led or (light near	U3-rurue:	1 3:4 0
-		mounted)) near10 (led or (light near emitting n ar (diode or device)))).ti.ab.clm.	US-PGPUB; EPO: JP :	15:40
-	[emitting n ar (diode or device)))).ti,ab,clm.	EPO; JP ; DERWENT;	15:40

				
-	16	((surface near (m unt rm unting or	USPAT;	2004/06/22
		mount d)) n ar10 (l d r (light near	US-PGPUB;	15:42
		mitting near (di de r d vice)))).ti,ab,clm.	EPO; JPO;	
		same ((metal or c nductive or ndu ting	DERWENT;	
		r gold r silver) near lay r).ti,ab, lm.	IBM_TDB	
-	1	((surface near (m unt or m unting r	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:45
		emitting near (diode or device)))).clm. same	EPO; JPO;	
		((metal or conductive or conducting or gold	DERWENT;	
		or silver) near layer).clm.	IBM_TDB	
-	2	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:46
		emitting near (diode or device)))).clm. same	EPO; JPO;	
		((electrode or metal or conductive or	DERWENT;	
		conducting or gold or silver) near	IBM_TDB	
		layer).clm.		
-	4	((surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)) near10 (led or (light near	US-PGPUB;	15:47
		emitting near (diode or device)))).clm. same	EPO; JPO;	
		((electrode or metal or conductive or	DERWENT;	
		conducting or gold or silver) near (electrode	IBM_TDB	
		or layer)).clm.		
-	393	((led or (light near emitting near (diode or	USPAT;	2004/06/22
		device)))).clm. and ((second or two or	US-PGPUB;	16:09
		upper or lower or top or bottom) near	EPO; JPO;	
		((electrode or metal or conductive or	DERWENT;	
		conducting or gold or silver) near (electrode	IBM_TDB	
	70	or layer))).clm.		
-	79	((led or (light near emitting near (diode or	USPAT;	2004/06/22
		device)))).clm. and (substrate near10	US-PGPUB;	16:10
		((second or two or upper or lower or top or	EPO; JPO;	
		bottom) near ((electrode or metal or	DERWENT;	
		conductive or conducting or gold or silver)	IBM_TDB	
	7	near (electrode or layer)))).clm.	HEDAT-	2004/06/22
_	'	(surface near (mount or mounting or	USPAT;	2004/06/22
		mounted)).ti,ab,clm. and ((led or (light near emitting near (diode or device)))).clm. and	US-PGPUB;	16:10
		(substrate near10 ((second or two or upper	EPO; JPO; DERWENT;	
		or lower or top or bottom) near ((electrode	IBM_TDB	
		or metal or conductive or conducting or	15M_108	
		gold or silver) near (electrode or		
		layer)))).clm.		
	291	((surface near (mount or mounting or	USPAT;	2004/06/22
	23.	mounted)) near10 (led or (light near	US-PGPUB;	16:13
		emitting))).clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	71	((surface n ar (m unt r mounting or	USPAT;	2004/06/22
		m unt d)) near10 (l d or (light n ar	US-PGPUB;	16:17
		mitting))).clm. and ((surfa e n ar (m unt	EPO; JPO;	
		rm unting rm unted)) n ar10 (led r	DERWENT;	
		(light near mitting))).ab.	IBM_TDB	
		777		<u> </u>

•	3320	two near metal n ar layer	USPAT;	2004/06/22
			US-PGPUB;	16:17
			EPO; JP ;	
			DERWENT;	
			IBM_TDB	
_	29	(two n ar metal near lay r) and (I d or	USPAT;	2004/06/22
		(light near emitting)) and (surface near	US-PGPUB;	16:20
		(mount or mounting or mounted))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
<u>-</u>	1	(two near metal near layer).clm. and (led or	USPAT;	2004/06/22
		(light near emitting)) and (surface near	US-PGPUB;	16:20
		(mount or mounting or mounted))	EPO; JPO;	
		(the and a second and a second a secon	DERWENT;	
			IBM_TDB	
_	10	(two near (silver or gold or conductive or	USPAT;	2004/06/22
		conducting or electrode or metal) near	US-PGPUB;	16:22
		layer).clm. and (led or (light near emitting))	EPO; JPO;	
		and (surface near (mount or mounting or	DERWENT;	
		mounted))	IBM_TDB	
_	2285	(two near2 (silver or gold or conductive or	USPAT;	2004/06/22
	2200	conducting or electrode or metal) near	US-PGPUB;	16:23
		layer) near10 (insulate or insulated or	EPO; JPO;	10123
]		insulating or insulation or isolate or	DERWENT;	
		isolated or isolating or isolation)	IBM_TDB	
_	280	((two near2 (silver or gold or conductive or	USPAT;	2004/06/22
_	200	conducting or electrode or metal) near	US-PGPUB;	
		layer) near10 (insulate or insulated or	EPO; JPO;	10.24
		insulating or insulation or isolate or	DERWENT;	
		isolated or isolating or isolation)).clm.	IBM_TDB	
<u>-</u>	7371	(((second or first or upper or lower or top or	USPAT;	2004/06/22
	1071	bottom or two) near2 (silver or gold or	US-PGPUB;	16:26
		conductive or conducting or electrode or	EPO; JPO;	10.20
		metal) near layer) near10 (insulate or	DERWENT;	
		insulated or insulating or insulation or	IBM_TDB	
		isolate or isolated or isolating or		
		isolation)).clm.		
_	1779	(((second or first or upper or lower or top or	USPAT;	2004/06/22
		bottom or two) near2 (silver or gold or	US-PGPUB;	16:25
		conductive or conducting or electrode or	EPO; JPO;	14124
		metal) near layer) near10 (insulate or	DERWENT;	
		insulated or insulating or insulation or	IBM_TDB	
		isolate or isolated or isolating or isolation)	15111_155	
		near10 substrate).clm.		
_	2	•	USPAT;	2004/06/22
		or bottom or two) near2 (silver or gold or	US-PGPUB;	16:28
		conductive or conducting or electrode or	EPO; JPO;	
		metal) near layer) n ar10 (insulate or	DERWENT;	
		insulated or insulating rinsulati n or	IBM_TDB	
		isolat ris lated or isolating r	15111_106	
		isolati n)).clm. same (substrat) same (l d	i	
		r (light near emitting)) same (surfa n ar		İ
		(m unt or mounting r mounted))).clm.		-
		tin ant or mounting 1 mounted))).cim.	L	